18. The method of claim 17, wherein the inner end portion of each lead has a lesser thickness than an adjacent remaining portion of the lead.

19. The method of claim 17, wherein the laser cutting forms a wide area and a narrow area on the inner end portion of each lead.

20. The method of claim 19, wherein the location of the wide area and the narrow area alternates on adjacent leads.

21. The method of claim 19, wherein the wide area and the narrow area comprise a wine-glass shape.

Cont'd A1

22. The method of claim 19, wherein the inner end portion of each lead has a lesser thickness than an adjacent remaining portion of the lead.

23. The method of claim 17, wherein the laser cutting forms at least two leads that are integrally joined.

24. The method of claim 23, wherein the two leads that are integrally joined are joined by a bar, and the combination of the two integrally joined leads and the bar encloses the other leads.

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42. (New) A semiconductor package made by the method of claim 17.

43. (New) A semiconductor package made by the method of claim 18.

A2

44. (New) A semiconductor package made by the method of claim 19.

45. (New) A semiconductor package made by the method of claim 20.

46. (New) A method of making a semiconductor package, the method comprising:

providing a leadframe including a plurality of leads, wherein at least a first portion of each lead is singulated by laser cutting;

electrically coupling a chip to the leads.

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47. (New) The method of claim 46, wherein the first portion of the leads has a lesser thickness than an outwardly adjacent portion of the lead, and the chip is electrically coupled to the first portion of the leads.

48. (New) The method of claim 46, wherein the first portion of the lead is an inner end of the lead.

49. (New) The method of claim 48, wherein the first portion of immediately adjacent ones of the leads have different widths.

Omitted A2

50. (New) The method of claim 46, wherein the first portion of immediately adjacent ones of the leads are mirror images.

51. (New) The method of claim 46, wherein the first portion of immediately adjacent ones of the leads are oppositely oriented T shapes.

52. (New) The method of claim 46, wherein the first portion of immediately adjacent ones of the leads are oppositely oriented wine glass shapes.

53. (New) The method of claim 46, wherein two of said leads are integrally coupled around the first portion of at least one other of said leads.

54. (New) The method of claim 46, wherein the first portion of immediately adjacent ones of the leads have different widths, and the chip is electrically coupled to the first portion of the leads.

55. (New) The method of claim 46, wherein the first portion of immediately adjacent ones of the leads are mirror images, and the chip is electrically coupled to the first portion of the leads.

56. (New) A semiconductor package made by the method of claim 46.

57. (New) A semiconductor package made by the method of claim 47.

58. (New) A semiconductor package made by the method of claim 53.

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59. (New) A semiconductor package made by the method of claim 54.

60. (New) A method of making a semiconductor package, the method comprising:

providing a leadframe including die pad and a plurality of leads extending toward the die pad, wherein at least a first portion of each lead is singulated by laser cutting, said first portion having a thickness less than a remaining thickness of an immediately adjacent outward portion of the lead;

electrically coupling an electrical conductor between a chip coupled to the die pad and the first portion of respective ones of said leads.

61. (New) The method of claim 59, wherein the first portion of immediately adjacent ones of the leads are mirror image shapes.

62. (New) The method of claim 59, wherein the first portion of immediately adjacent ones of the leads are oppositely oriented wine glass shapes or oppositely oriented T shapes.

63. (New) The method of claim 59, wherein two of said leads are integrally coupled around the first portion of at least one other of said leads.

64. (New) The method of claim 60, wherein the first portion of immediately adjacent ones of the leads have different widths and in of alternating shapes.

65. (New) A semiconductor package made by the method of claim 60.

66. (New) A semiconductor package made by the method of claim 61.

67. (New) A semiconductor package made by the method of claim 63.

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REMARKS

Group II is elected. The new claims are Group II claims. An Information Disclosure Statement accompanies this response.

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